

Appl. No. 09/989,931

DRAFT CLAIMS FOR DISCUSSION PURPOSES ONLY**Amendments to the Claims**

22. (Currently Amended) An integrated circuit package separator for separating a plurality of integrated circuit packages from one another, the integrated circuit packages being provided as integrated circuit chip components joined to a board, the separating including cutting the board, the separator comprising:

a panel;

a plurality of blocks over the panel, the plurality of blocks having curved upper surfaces and configured to form a recessed portion over an uppermost surface of the panel, the blocks and being configured to support the board while leaving the integrated circuit chip components in the recessed portion extending between the block upper surfaces and the uppermost surface of the panel;

a cutting mechanism configured to cut the board while the board is supported on the blocks and to thereby separate the integrated circuit packages from one another; and

wherein the panel is immobile relative the plurality of the blocks.

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110. (Currently Amended) An integrated circuit package separator for separating a plurality of integrated circuit packages from one another, the integrated circuit packages being provided as integrated circuit chip components joined to a board, the separating including cutting the board, the separator comprising:

a panel having an uppermost surface and molded as part of the separator;

a plurality of blocks formed as one piece with the panel and extending upward from the uppermost surface of the panel thereby creating a recessed portion on the panel, the plurality of blocks configured to support the board leaving the integrated circuit chip components extending in the recessed portion between the blocks and the uppermost surface of the panel; and

a cutting mechanism configured to cut the board while the board is supported on the blocks and to thereby separate the integrated circuit packages from one another.

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115. (Currently Amended) An integrated circuit package separator, comprising:

a panel, wherein integrated circuit packages are provided as integrated circuit chip components joined to a board;

a plurality of ribs over the panel, the ribs having curved upper surfaces and being configured to support the board while providing the integrated circuit chip components on an underside of the board in recessed slots configured to extend between upper surfaces of the ribs and an uppermost surface of the panel;

a cutting mechanism configured to cut the board while the board is supported on ~~the~~ a plurality of blocks and to thereby separate the integrated circuit packages from one another; and

wherein the panel is immobile relative the plurality of the blocks, during separation of a plurality of integrated circuit packages from one another.